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March 2015

FDD3706/FDU3706

20V N-Channel PowerTrench® MOSFET

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON), fast switching speed and extremely low R_{DS(ON)} in a small package.

Applications

- DC/DC converter
- Motor Drives

Features

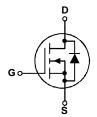
• 50 A, 20 V $R_{DS(ON)} = 9 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$ $R_{DS(ON)}$ = 11 m Ω @ V_{GS} = 4.5 V $R_{DS(ON)} = 16 \text{ m}\Omega$ @ $V_{GS} = 2.5 \text{ V}$

- Low gate charge (16 nC)
- · Fast Switching
- High performance trench technology for extremely low $R_{DS(ON)}$









Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DSS}	Drain-Source Voltage			20	V
V _{GSS}	Gate-Source Voltage			± 12	V
I _D	Continuous Drain Current	@T _C =25°C	(Note 3)	50	Α
		@T _A =25°C	(Note 1a)	14.7	
		Pulsed	(Note 1a)	60	
P _D	Power Dissipation	@T _C =25°C	(Note 3)	44	W
		@T _A =25°C	(Note 1a)	3.8	
		@T _A =25°C	(Note 1b)	1.6	
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +175	°C

Thermal Characteristics

R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	3.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	45	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	96	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape width	Quantity
FDD3706	FDD3706	D-PAK (TO-252)	13"	16mm	2500 units
FDU3706	FDU3706	I-PAK (TO-251)	Tube	N/A	75

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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-Sc	ource Avalanche Ratings (Not	e 2)	I			
E _{AS}	Drain-Source Avalanche Energy	Single Pulse, V _{DD} = 10V, I _D =7A			60	mJ
I _{AS}	Drain-Source Avalanche Current				7	Α
Off Char	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	20			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA,Referenced to 25°C		13		mV/°(
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16 V, V _{GS} = 0 V			1	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	V _{GS} = 12 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V}$ $V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.5	1	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A,Referenced to 25°C		-3.5		mV/°(
$R_{DS(on)}$	Static Drain–Source On–Resistance	$ \begin{aligned} &V_{GS} = 10 \text{ V}, & I_D = 16.2 \text{ A} \\ &V_{GS} = 4.5 \text{ V}, & I_D = 14.7 \text{ A} \\ &V_{GS} = 2.5 \text{ V}, & I_D = 12.2 \text{ A} \\ &V_{GS} = 4.5 \text{ V}, I_D = 14.7 \text{ A}, T_J = 125^{\circ}\text{C} \end{aligned} $		7.5 8 11 12.6	9 11 16 19	mΩ
I _{D(on)}	On–State Drain Current	$V_{GS} = 4.5 \text{ V}, \qquad V_{DS} = 5 \text{ V}$	30			Α
g FS	Forward Transconductance	$V_{DS} = 5 \text{ V}, \qquad I_{D} = 14.7 \text{ A}$		65		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance			1882		pF
C _{oss}	Output Capacitance	$V_{DS} = 10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		430		pF
C _{rss}	Reverse Transfer Capacitance	f = 1.0 MHz		201		pF
Switchin	ng Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time			11	20	ns
t _r	Turn-On Rise Time	$V_{DD} = 10 \text{ V}, \qquad I_{D} = 1 \text{ A},$		15	27	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		35	56	ns
t _f	Turn-Off Fall Time			16	29	ns
Qq	Total Gate Charge			16	23	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = 10V$, $I_{D} = 14.7 A$, $V_{GS} = 4.5 V$		3.7		nC
Q _{gd}	Gate-Drain Charge	VGS - 4.5 V		4		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
I _s	Maximum Continuous Drain-Source			3.2	Α	
V _{SD}	Drain–Source Diode Forward Voltage $V_{GS} = 0 \text{ V}$, $I_S = 3.2 \text{ A}$ (Note 2)			0.7	1.2	V

1. R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $\rm R_{\theta JC}$ is guaranteed by design while $\rm R_{\theta CA}$ is determined by the user's board design.



Scale 1: 1 on letter size paper

2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

 $\sqrt{\frac{P_D}{R_{DS(ON)}}}$ 3. Maximum current is calculated as:

where P_D is maximum power dissipation at T_C = 25°C and $R_{DS(on)}$ is at $T_{J(max)}$ and V_{GS} = 10V. Package current limitation is 21A

Typical Characteristics

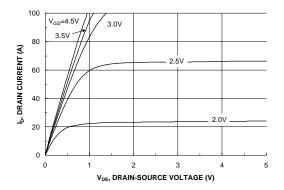


Figure 1. On-Region Characteristics

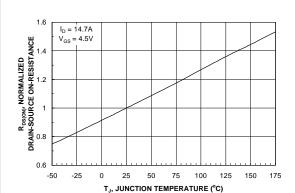


Figure 3. On-Resistance Variation withTemperature

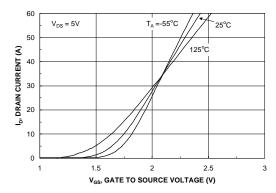


Figure 5. Transfer Characteristics

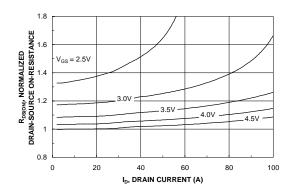


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

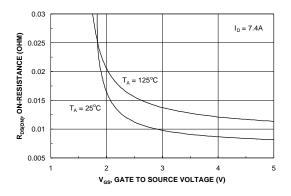


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

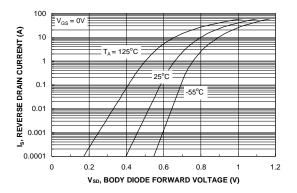
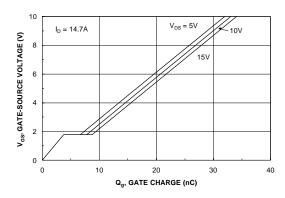


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics



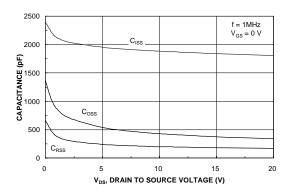


Figure 7. Gate Charge Characteristics

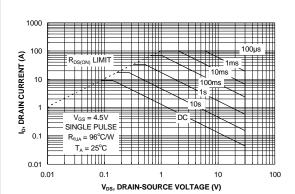


Figure 8. Capacitance Characteristics

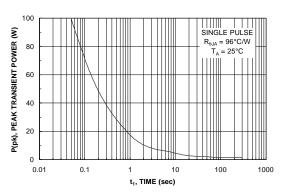


Figure 9. Maximum Safe Operating Area



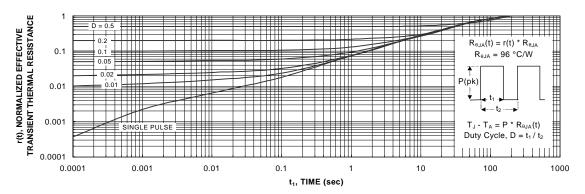


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



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